

IN THE SPECIFICATION

Following is a marked-up version of each amended paragraph of the subject patent application. The Examiner is requested to delete the indicated paragraph and replace it with the amended paragraph.

Replace paragraph [0021] with the following:

[0021] The ground plane 20, the conductive intermediate layer 24 26 and the top layer 28 are formed from conductive material layers disposed on dielectric substrates, such as copper-clad printed circuit board material (also referred to as FR4). The conductive material layers are patterned, masked and etched to form the desired features of the ground plane 20, the conductive intermediate layer 24 26 and the top layer 28. Thus the antenna 18 can be fabricated by employing conventional single and multilayer printed circuit board fabrication techniques.

Replace paragraph [0022] with the following:

[0022] For example, a first double-clad dielectric substrate is processed to form the features of the ground plane 20 and the conductive intermediate layer 2426. A second single-clad dielectric substrate is processed to form the features of the top layer 28. A thin adhesive bonding layer is applied to one or both of the mating surfaces of the two dielectric substrates (that is, the conductive intermediate layer 24 26 of the first dielectric substrate and a bottom surface of the second dielectric substrate). The two dielectric substrates are brought into contact and pressure is applied to form the antenna 18.

After paragraph [0016], please add the following text:

Figure 12 is a bottom view of another embodiment of an antenna constructed according to the teachings of the present invention.

Figure 13 is a top view of yet another embodiment of an antenna constructed according to the teachings of the present invention.

Immediately following paragraph [0047], please add the following text:

Figure 12 illustrates an embodiment of an antenna constructed according to the teachings of the present invention comprising a ground plane 150 to which are electrically connected

conductive vias 30, 31 and 152, which are further connected to conductive regions 28A, 28C and 28D, respectively. The signal via 32 is connected between the conductive region 28A and a signal feed (neither illustrated in Figure 12).

Figure 13 illustrates an embodiment of the present invention wherein a ground plane 160 extends beyond side surfaces of the stacked structure comprising the dielectric layer 22, the conductive intermediate layer 24 and the dielectric layer 26 (see Figure 2).